

IN THE CLAIMS:

This Listing of Claims will replace all prior versions, and listings, of claims in the subject Patent Application:

Listing of Claims:

1. (Currently amended) An injection encapsulating process for a 3D-animation cup, ~~wherein, comprising the steps of:~~

capturing and rolling directly against a surface of an inner cup an image layer bearing a 3D-image, said 3D-image being thereby ~~animation~~ first transferred to an said inner cup surface,

~~followed by a capturing and rolling transfer of a thermal~~ [[withstanding]] protection layer to against the exterior of said 3D-image on said inner cup surface, animation layer, then a transfer of both said 3D-animation layer and said thermal [[withstanding]] protection layer being thereby transferred onto the surface of the inner cup over said 3D-image, finally, and

placing the inner cup having the transferred with said 3D-image animation layer and the thermal [[withstanding]] protection layer placed in a dies assembly to be encapsulated by and become an integrated part with an injection molded transparent outer cup formed thereabout.

2. (New) The process as recited in Claim 1, wherein said step of capturing and rolling said image and thermal protection layers includes the use of a thermally protected silicon rubber roll member.